

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Do Hyoung KANG</td> <td>03/02/2012</td> </tr> <tr> <td>Oh Sug KIM</td> <td>03/02/2012</td> </tr> </tbody> </table>		Name	Execution Date	Do Hyoung KANG	03/02/2012	Oh Sug KIM	03/02/2012
Name	Execution Date						
Do Hyoung KANG	03/02/2012						
Oh Sug KIM	03/02/2012						
RECEIVING PARTY DATA							
Name:	SEOUL SEMICONDUCTOR CO., LTD.						
Street Address:	1B-25, 727, Wonsi-dong, Danwon-gu						
Internal Address:	Gyeonggi-do						
City:	Ansan-city						
State/Country:	REPUBLIC OF KOREA						
Postal Code:	425-851						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13410399</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13410399		
Property Type	Number						
Application Number:	13410399						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Hae-Chan Park						
Total Attachments: 3 source=P4779US00_Assignment#page1.tif source=P4779US00_Assignment#page2.tif source=P4779US00_Assignment#page3.tif							

OP \$40.00 13410399



### ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled **LIGHT EMITTING DIODE PACKAGE** ("Application");

upon which United States Letters Patent, Patent Number \_\_\_\_\_, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

**Seoul Semiconductor Co., Ltd.**  
1B-25, 727, Wonsi-dong, Danwon-gu,  
Ansan-city, Gyeonggi-do, 425-851  
Republic of Korea

**Seoul Semiconductor Co., Ltd.** herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.



IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Do Hyoung KANG

Address: 1B-25, 727, Wonsi-dong, Danwon-gu,  
Ansan-city, Gyeonggi-do, 425-851  
Republic of Korea

First Inventor's Signature:

Date:

2012. 03. 22

Second Inventor's Name: Oh Sug KIM

Address: 1B-25, 727, Wonsi-dong, Danwon-gu,  
Ansan-city, Gyeonggi-do, 425-851  
Republic of Korea

Second Inventor's Signature:

Date:



IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Do Hyoung KANG

Address: 1B-25, 727, Wonsi-dong, Danwon-gu,  
Ansan-city, Gyeonggi-do, 425-851  
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First Inventor's Signature: \_\_\_\_\_

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Second Inventor's Name: Oh Sug KIM

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Republic of Korea

Second Inventor's Signature: \_\_\_\_\_

*Oh Sug Kim*

Date: \_\_\_\_\_

*2012. 3. 2*